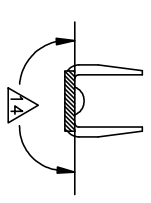
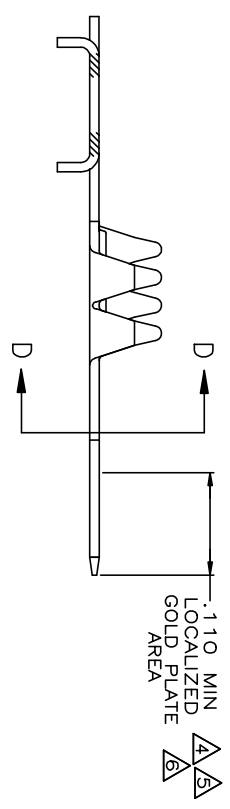
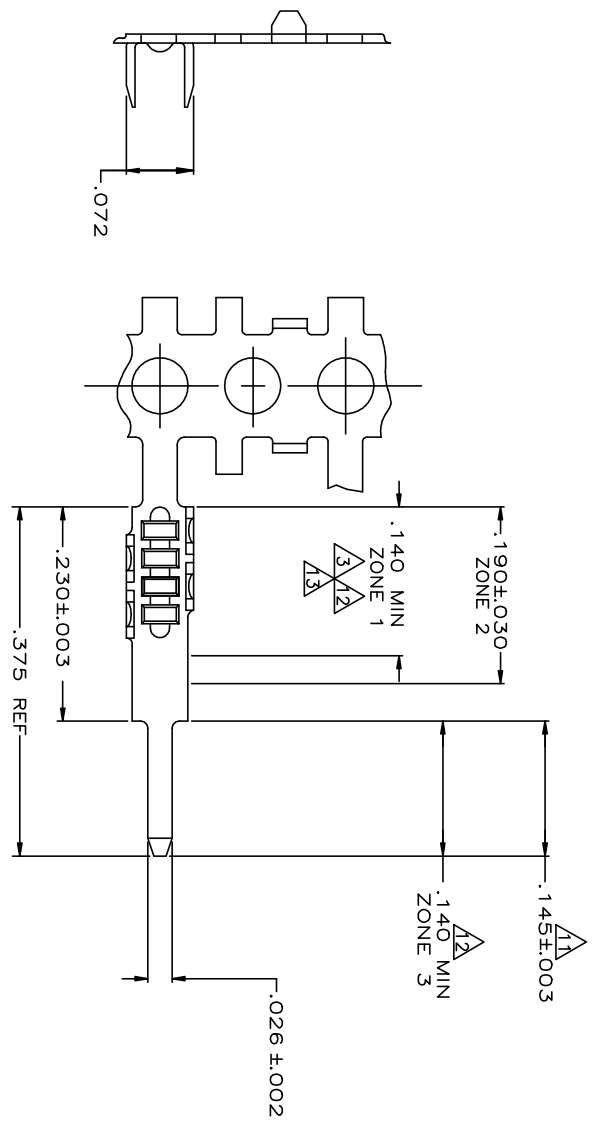


REVISIONS					
P	DATE	DESCRIPTION	DATE	BY	APP'D
12		REVISED PER ECR-23-193756	01DEC2023	GC	WH



- △.000050 MIN THK NICKEL UNDERPLATE OVER ENTIRE CONTACT.
- △.000150 MIN BRIGHT TIN/LEAD OVER ENTIRE CONTACT.
- △.000100 MIN THK BRIGHT TIN/LEAD IN ZONE 1.
- △GOLD FLASH IN LOCALIZED GOLD PLATE AREA.
- △.000015 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- △.000030 MIN GOLD IN LOCALIZED GOLD PLATE AREA
- 7. TO BE APPLIED PER AMP APPLICATION SPEC 114-16015.
- 8. RECOMMENDED HOLE SIZE IS .031-.035 DIA. FOR SOLDERABILITY SEE AMP PRODUCT SPEC 108-9024.
- △.000150 MIN TIN-LEAD IN ZONE 2.
- △.000150 MIN TIN-LEAD IN ZONE 1.
- △.000150 MIN TIN IN ZONE 3.
- △GOLD FLASH IN ZONE 1.
- △GOLD FLASH IN ZONE 1.
- △GOLD FLASH IN ZONE 1.
- △.000150 MIN TIN ENTIRE CONTACT.

REV	DATE	DESCRIPTION	BY	APP'D
1		2-88997-2		
2		2-88997-7		
3		1-88997-4		
4		1-88997-3		
5		1-88997-2		
6		88997-9		
7		88997-5		
8		88997-4		
9		88997-3		
10		88997-2		

SUPERSEDED BY 88997-5

THIS DRAWING IS A CONTROLLED DOCUMENT.		DATE	10/04/04	REV	10/04/04
DIM		MOCHASTER	10/04/04	CHK	BOLASH
DESIGNER		WALSHLEY	10/04/04	APP'D	WALSHLEY
PRODUCT SPEC		108-9024			
APPLICATION SPEC		114-16015			
MATERIAL		PH. BRONZE .010 THK			
FINISH		SEE TABLE			
CUSTOMER DRAWING		A2	00779	88997	
SCALE		10:1	SHEET	1	OF 1

STE TE Connectivity

CONTACT, SOLDER TAB, FPC, .100 Q